

CLAIMS

What is claimed is:

1. A manufacturing method of a component for the inkjet print head, which comprises the steps of:
 - 5 providing a substrate;
 - forming a sacrifice layer on a surface of the substrate;
 - forming a metal conductive circuit on sacrifice layer;
 - forming a first photosensitive polymer layer on the metal conductive circuit;
 - 10 forming more than one orifice and more than one through hole on the first photosensitive polymer layer by photolithography, the orifices allowing a fluid to flow through and the through holes being exposed from a lead end of the metal conductive circuit; and
 - removing the sacrifice layer so that the photosensitive polymer layer and the metal conductive circuit attached thereon depart from the substrate.
- 15 2. The manufacturing method of claim 1, wherein the step of forming a metal conductive circuit on the sacrifice layer uses the electroforming method.
3. The manufacturing method of claim 1, wherein the sacrifice layer is formed from a non-metal material and a step of forming an electroforming seed layer on the sacrifice layer is performed before the step of forming a metal conductive circuit on the sacrifice
20 layer.
4. The manufacturing method of claim 1, wherein the sacrifice layer is made of a metal material.

5. The manufacturing method of claim 1, wherein the step of forming a metal conductive circuit on the sacrifice layer forms a metal layer on the sacrifice layer first and then etches the metal layer to form the desired metal conductive circuit by photolithography.

5 6. The manufacturing method of claim 1 further comprising the step of forming a fluid structure with a plurality of ink chambers, each of which corresponds to and connects to one of the orifices.

7. The manufacturing method of claim 6, wherein the step of forming a fluid structure with a plurality of ink chambers first forms a second photosensitive polymer layer on the first photosensitive polymer layer and then forms the fluid structure by photolithography.

8. The manufacturing method of claim 1 further comprising the step of forming a passivation layer on the metal conductive circuit, wherein the passivation layer is formed on the surface of the metal conductive circuit other than that attached to the first photosensitive polymer layer.

9. A print head component comprising:

a photosensitive polymer substrate, which has more than one orifice for a fluid to flow through, the orifices being formed by photolithography; and

20 a metal conductive circuit, which is installed on the photosensitive polymer substrate and has a front end and a lead end, the front end receiving external signals and the lead end providing electrical connections with a chip and being exposed from the photosensitive polymer substrate.

10. The print head component of claim 9 further comprising a fluid structure combined with the photosensitive polymer substrate, wherein the fluid structure has a plurality of ink chambers corresponding to and connecting to the orifices.

11. The print head component of claim 10, wherein the fluid structure has a plurality of channels for providing the ink to the ink chambers.

12. The print head component of claim 9 further comprising a passivation layer formed on the surface of the metal conductive circuit other than that attached to the first
5 photosensitive polymer substrate.